ABSTRACT

SUPER THIN/SUPER THERMAL BALL GRID ARRAY PACKAGE

A package is provided for the packaging of semiconductor devices with a semiconductor substrate. In the first embodiment, a copper foil is attached to the substrate. In the second embodiment an adhesive film is attached to the substrate. The die is attached to the copper foil under the first embodiment and to the film under the second embodiment. The die is wire bonded and provided with a molding around the die. For the second embodiment, the film is replaced with a copper foil. Both embodiments have solder balls attached to the substrate and are singulated. (Fig. 4)